

PATENT ASSIGNMENT COVER SHEET

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EPAS ID: PAT2731191

SUBMISSION TYPE:	NEW ASSIGNMENT												
NATURE OF CONVEYANCE:	ASSIGNMENT												
CONVEYING PARTY DATA													
<table border="1"> <thead> <tr> <th>Name</th> <th>Execution Date</th> </tr> </thead> <tbody> <tr> <td>SOON-KANG HUANG</td> <td>01/27/2014</td> </tr> <tr> <td>HAN-HSIN KUO</td> <td>01/27/2014</td> </tr> <tr> <td>CHI-MING YANG</td> <td>02/05/2014</td> </tr> <tr> <td>SHWANG-MING JENG</td> <td>01/27/2014</td> </tr> <tr> <td>CHIN-HSIANG LIN</td> <td>01/27/2014</td> </tr> </tbody> </table>		Name	Execution Date	SOON-KANG HUANG	01/27/2014	HAN-HSIN KUO	01/27/2014	CHI-MING YANG	02/05/2014	SHWANG-MING JENG	01/27/2014	CHIN-HSIANG LIN	01/27/2014
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CHIN-HSIANG LIN	01/27/2014												
RECEIVING PARTY DATA													
Name:	TAIWAN SEMICONDUCTOR MANUFACTURING COMPANY, LTD.												
Street Address:	NO. 8, LI-HSIN RD. 6, SCIENCE-BASED INDUSTRIAL PARK												
City:	HSIN-CHU												
State/Country:	TAIWAN												
Postal Code:	300-77												
PROPERTY NUMBERS Total: 1													
<table border="1"> <thead> <tr> <th>Property Type</th> <th>Number</th> </tr> </thead> <tbody> <tr> <td>Application Number:</td> <td>14182912</td> </tr> </tbody> </table>		Property Type	Number	Application Number:	14182912								
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Application Number:	14182912												
CORRESPONDENCE DATA													
Fax Number:	(214)200-0853												
Phone:	214-651-5000												
Email:	ipdocketing@haynesboone.com												
<i>Correspondence will be sent via US Mail when the email attempt is unsuccessful.</i>													
Correspondent Name:	HAYNES AND BOONE, LLP IP SECTION												
Address Line 1:	2323 VICTORY AVENUE												
Address Line 2:	SUITE 700												
Address Line 4:	DALLAS, TEXAS 75219												
ATTORNEY DOCKET NUMBER:	24061.2788												
NAME OF SUBMITTER:	LINDA INGRAM												

Signature:	/Linda Ingram/
Date:	02/18/2014
<p>Total Attachments: 15 source=2788_Assignment#page1.tif source=2788_Assignment#page2.tif source=2788_Assignment#page3.tif source=2788_Assignment#page4.tif source=2788_Assignment#page5.tif source=2788_Assignment#page6.tif source=2788_Assignment#page7.tif source=2788_Assignment#page8.tif source=2788_Assignment#page9.tif source=2788_Assignment#page10.tif source=2788_Assignment#page11.tif source=2788_Assignment#page12.tif source=2788_Assignment#page13.tif source=2788_Assignment#page14.tif source=2788_Assignment#page15.tif</p>	

A S S I G N M E N T

WHEREAS, we,

- | | | | |
|-----|------------------|----|---|
| (1) | Soon-Kang Huang | of | 40-1, Alley 14, Lane 452, Bao San Road
Hsin Chu Taiwan R.O.C. |
| (2) | Han-Hsin Kuo | of | No. 85, Sec. 2, Jhinghua S. Rd.
South District, Tainan City
Taiwan, R.O.C. |
| (3) | Chi-Ming Yang | of | No. 4, Ln. 67, Dunfeng Rd.
Xiangshan District
Hsinchu City 300, Taiwan R.O.C. |
| (4) | Shwang-Ming Jeng | of | 9F No. 19 22nd alley Nan-Chung Street
Hsin-Chu, Taiwan, R.O.C. |
| (5) | Chin-Hsiang Lin | of | No. 37, Lane 393, Min-Hu Road
Hsin-Chu, Taiwan, R.O.C. |

have invented certain improvements in

METAL CONDUCTOR CHEMICAL MECHANICAL POLISH

for which we have executed an application for Letters Patent of the United States of America,

 of even date filed herewith; and
 X filed on February 18, 2014, and assigned application number 14/182,912; and

WHEREAS, we authorize the attorney of record to update this document to include Patent Office information as deemed necessary (i.e., filing date, serial number, etc.);

WHEREAS, Taiwan Semiconductor Manufacturing Company, Ltd., (“TSMC”), No. 8, Li-Hsin Rd. 6, Science-Based Industrial Park Hsin-Chu, Taiwan 300-77, Republic of China. is desirous of obtaining the entire right, title, and interest in, to and under the said invention and the said application in the United States of America and in any and all countries foreign thereto;

NOW, THEREFORE, for good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, and other good and valuable consideration, we have sold, assigned, transferred and set over, and by these presents do hereby sell, assign, transfer and set over, unto the said TSMC, its successors, legal representatives, and assigns, the entire right, title, and interest in, to and under the said invention, and the said application, and all divisional, renewal, substitutional, and continuing applications thereof, and all Letters Patent of the United States of America which may be granted thereon and all reissues and extensions thereof, and all applications for Letters Patent which may be filed for said invention in any country or countries foreign to the United States of America, and all extensions, renewals, and reissues thereof, and all prior patents and patent applications from which a filing priority of the above-described patent application may be obtained, including the right to collect past damages; and we hereby authorize and request the Commissioner of Patents of the United States of America, and any official of any

country or countries foreign to the United States of America, whose duty it is to issue patents on applications as aforesaid, to issue all Letters Patent for said invention to the said TSMC, its successors, legal representatives and assigns, in accordance with the terms of this instrument.

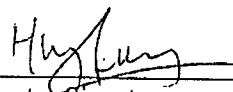
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Inventor Name: Soon-Kang Huang

Residence Address: 40-1, Alley 14, Lane 452, Bao San Road, Hsin Chu Taiwan R.O.C.

Dated: Jan. 27, 2014



Inventor Signature

Inventor Name: Han-Hsin Kuo

Residence Address: No. 85, Sec. 2, Jhinghua S. Rd., South District, Tainan City
Taiwan, R.O.C.

Dated: _____

Inventor Signature

Inventor Name: Chi-Ming Yang

Residence Address: No. 4, Ln. 67, Dufeng Rd., Xiangshan District
Hsinchu City 300, Taiwan R.O.C.

Dated: _____

Inventor Signature

Inventor Name: Shwang-Ming Jeng

Residence Address: 9F No. 19 22nd alley Nan-Chung Street, Hsin-Chu, Taiwan, R.O.C.

Dated: _____

Inventor Signature

Inventor Name: Chin-Hsiang Lin

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Residence Address: 40-1, Alley 14, Lane 452, Bao San Road, Hsin Chu Taiwan R.O.C.

Dated: _____

Inventor Signature

Inventor Name: Han-Hsin Kuo

Residence Address: No. 85, Sec. 2, Jhinghua S. Rd., South District, Tainan City
Taiwan, R.O.C.

Dated: 2014/01/27

Han-Hsin Kuo

Inventor Signature

Inventor Name: Chi-Ming Yang

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Hsinchu City 300, Taiwan R.O.C.

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Docket No.: 2010-0368-D / 24061.2788

Customer No.: 000042717

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Chi-Ming Yang

7/5, 2014

Inventor Signature

Inventor Name: Shwang-Ming Jeng

Residence Address: 9F No. 19 22nd alley Nan-Chung Street, Hsin-Chu, Taiwan, R.O.C.

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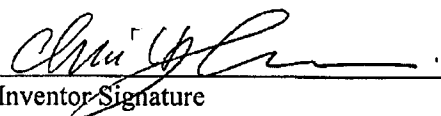
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Inventor Name: Chin-Hsiang Lin

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